

## TRANSMITTAL FORM

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June 18, 2003 (Date of Deposit)

Box Patent Application Assistant Commissioner For Patents Washington, D.C. 20231

Attorney Doc. #: Mailing Date:

68,700-015

Dear Sir:

Transmitted herewith for filing is the patent application of:

Inventor(s):

Kuo-Lung Lei

For:

## MEMS MICRO-CAP WAFER LEVEL CHIP SCALE PACKAGE

Submitted herewith are:

\_X \_\_ 2 \_\_ sheet(s) of formal drawings

X An Assignment of the invention to Aptos Corporation, together with Assignment Recordal Sheet

X A Declaration for patent application under CFR 1.63 and 1.68

The filing fee has been calculated as shown below:

	No. Filed	No. Extra	Small Entity Fee	Large Entity Fee	Total
Basic Fee			\$375.00	\$750.00	\$375.00
Total Claims	25x20	5 x	\$9.00	\$18.00	\$45.00
Indep. Claims	3-3	0 x	\$42.00	\$84.00	\$0
Multiple Dep. Clms.			\$140.00	\$280.00	\$0
Assign. Rec. Fee			\$40.00	\$40.00	\$40.00
TOTAL					\$460.00

Mailing Date: Uthe 18,2003 Attorney Docket No.: <u>68 700 -015</u>

X	Attached is a Credit Card Payment Form for the sum of \$_460.00
X	Charge Visa Credit Card No the sum of \$
X	The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Visa Credit Card No. A duplicate copy of this sheet is enclosed.
	Any additional filing fees required under 37 CFR 1.6 Any patent application processing fees under 37 CFR 1.17
	Respectfully abmitted

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RWT/kd Enclosures